TOSHIBA BIPOLAR DIGITAL INTEGRATED CIRCUIT SILICON MONOLITHIC

# TD62781AP,TD62781F,TD62781AF TD62782AP,TD62782F,TD62782AF

### 8CH HIGH-VOLTAGE SOURCE DRIVER

The TD62781AP / F / AF Series are comprised of eight source current Transistor Array.

These drivers are specifically designed for fluorescent display applications.

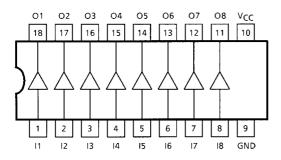
Applications include relay, hammer and lamp drivers.

### FEATURES

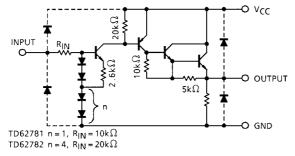
- High output voltage Type-AP, AF:  $V_{OUT} = 60 V$  (Min) Type-F :  $V_{OUT} = 35 V$  (Min)
- Output current (single output) IOUT = -50 mA / ch (Max)
- Pull-down resistors / each output
- Single supply voltage
- Input compatible with various types of logic

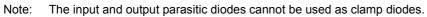
TYPE	DESIGNATION			
TD62781AP / F / AF	TTL, 5 V CMOS			
TD62782AP / F / AF	6~15 V PMOS CMOS			

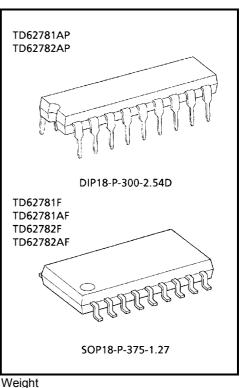
#### **PIN CONNECTION (TOP VIEW)**



### SCHEMATICS (EACH DRIVER)







DIP18-P-300-2.54D : 1.47 g (Typ.) SOP18-P-375-1.27 : 0.41 g (Typ.)

# MAXIMUM RATINGS (Ta = 25°C)

CHARACTE	RISTIC	SYMBOL	RATING	UNIT	
Supply Voltage	AP / AF	Vcc	60	V	
Supply Voltage	F	vcc	35		
Output Voltage		V <sub>OUT</sub>	V <sub>CC</sub>	V	
Output Current		IOUT	-50	mA / ch	
Input Voltage		V <sub>IN</sub>	20	V	
Power Dissipation	AP	P <sub>D</sub> (Note)	1.47	w	
Power Dissipation	F / AF	PD (Note)	0.96	vv	
Operating Temperature	•	T <sub>opr</sub>	-40~85	°C	
Storage Temperature		T <sub>stg</sub>	-55~150	°C	

Note: Delated above 25°C in the proportion 11.7 mW / °C (AP Type), 7.7 mW / °C (F, AF Type).

# **RECOMMENDED OPERATING CONDITIONS (Ta = -40~85°C)**

CHARACTERISTIC		SYMBOL	CONDITION	MIN	TYP.	MAX	UNIT	
Supply	TD62781AP, TD62781AF				4.5	_	55	v
	TD62781F				4.5	_	35	
Voltage	TD62782A	P, TD62782AF	V <sub>CC</sub>	—	6.0	_	55	v
	TD62782F				6.0	_	35	
Output Volt	age		V <sub>OUT</sub>	_	0	_	V <sub>CC</sub>	V
Output Cur	tput Current		I <sub>OUT</sub>	—	0	_	-40	mA / ch
Input Voltage	TD62781		VIN	_	0	_	7	v
	TD62782				0	_	15	
Dowor Diog	AP AP		D-	_	_	_	0.52	w
Power Dissipation		AF / F	PD	—	_	—	0.35	vv

# ELECTRICAL CHARACTERISTICS (Ta = 25°C)

CHARACTERISTIC			SYMBOL	TEST CIR- CUIT	TEST CONDITION	MIN	TYP.	MAX	UNIT
Input Voltage	"H" Level	TD62781	- V <sub>IH</sub>	1		2.0	_	_	V
		TD62782				4.5	_	_	
	"L" Level	TD62781	V <sub>IL</sub> 1			0	_	0.8	V
		TD62782			—	0	_	2.0	
Input Current	"H" Level	TD62781		2	V <sub>IN</sub> = 2.4 V		40	75	μΑ
		TD62782	Ιн	2	V <sub>IN</sub> = 7.5 V		170	250	
Output Current "H" Level		"H" Level	I <sub>OL</sub>	3	—		200		μA
Output Voltage "H" Level		V <sub>OH</sub>	4	I <sub>OUT</sub> = -40 mA, V <sub>IN</sub> = V <sub>IH MIN</sub> .	V <sub>CC</sub> -2.5	V <sub>CC</sub> −1.7	_	V	
		"L" Level	V <sub>OL</sub>		I <sub>OUT</sub> = 0, V <sub>IN</sub> = V <sub>IL MIN</sub> .		50	250	mV
Supply Current		ICC (ON)	- 1	$V_{CC}$ = 55 V, $V_{IN}$ = $V_{IH MIN.}$ (Note)	_	_	20	mA	
		ICC (OFF)		$V_{CC}$ = 55 V, $V_{IN}$ = $V_{IL MAX.}$ (Note)	_	_	1	mA	
Turn-On Delay		t <sub>ON</sub>	5	V <sub>CC</sub> = 55 V, C <sub>L</sub> = 15 pF	_	0.2	_		
Turn-Off Delay			tOFF	5	(Note)	_	6.0	_	μs

Note: V<sub>CC</sub> = 35 V for Type-F

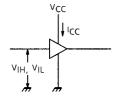
# **TEST CIRCUIT**

 $1. \quad V_{IH}, \, V_{IL}, \, I_{CC}$ 

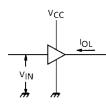
2. I<sub>IH</sub>

4.

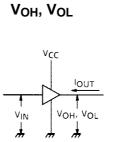
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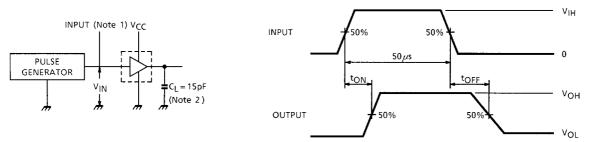




### 5. t<sub>ON</sub>, t<sub>OFF</sub>



Vcc



Note 1: Pulse Width 50 µs, Duty Cycle 10%

Output Impedance 50  $\Omega$ , t<sub>r</sub> ≤ 100 ns, t<sub>f</sub> ≤ 100 ns

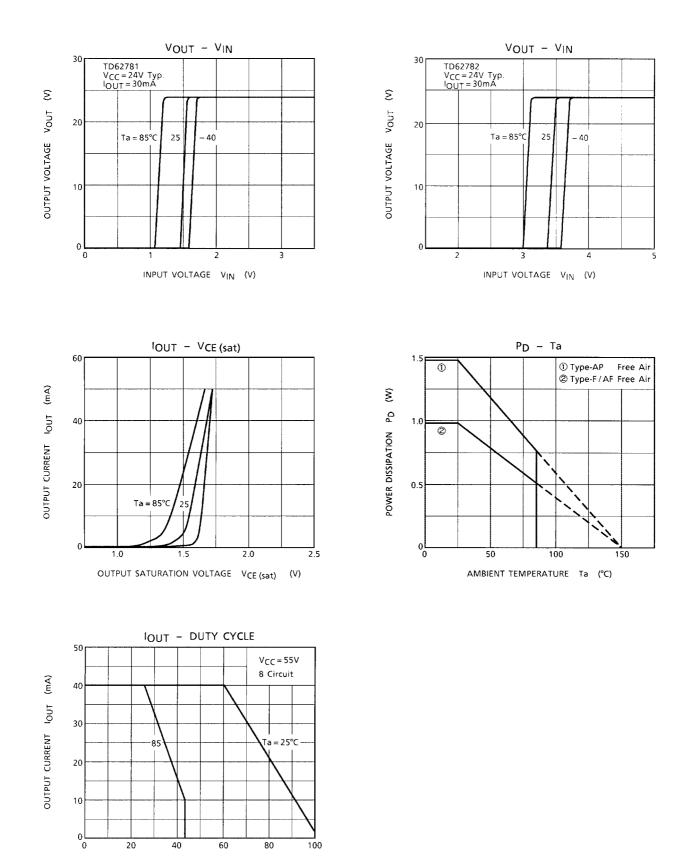
Note 2:  $C_L$  includes probe and jig capacitance.

# **PRECAUTIONS for USING**

This IC does not integrate protection circuits such as overcurrent and overvoltage protectors.

Thus, if excess current or voltage is applied to the IC, the IC may be damaged. Please design the IC so that excess current or voltage will not be applied to the IC.

Utmost care is necessary in the design of the output line,  $V_{CC}$  and GND line since IC may be destroyed due to short-circuit between outputs, air contamination fault, or fault by improper grounding.

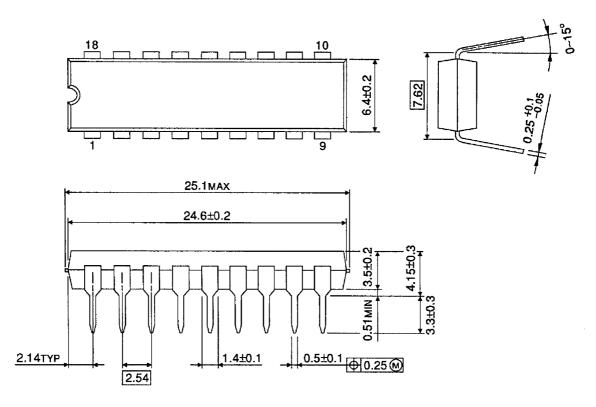


DUTY CYCLE (%)

#### PACKAGE DIMENSIONS

DIP18-P-300-2.54D

Unit: mm

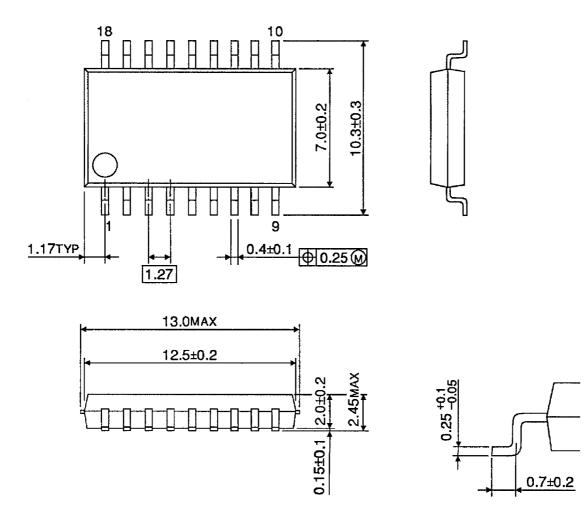


Weight: 1.47 g (Typ.)

### PACKAGE DIMENSIONS

SOP18-P-375-1.27

Unit: mm



Weight: 0.41 g (Typ.)

### **RESTRICTIONS ON PRODUCT USE**

Handbook" etc..

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